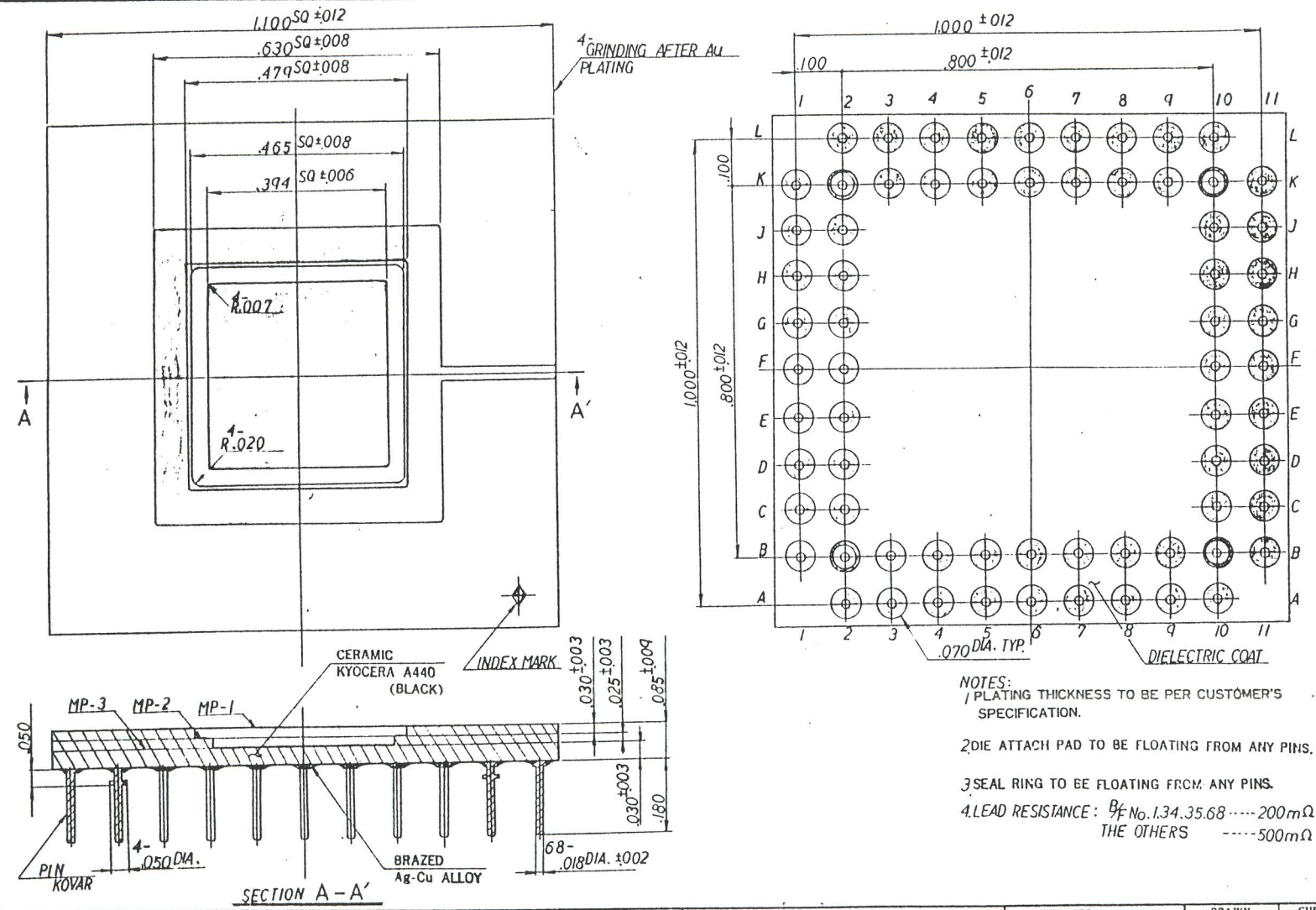
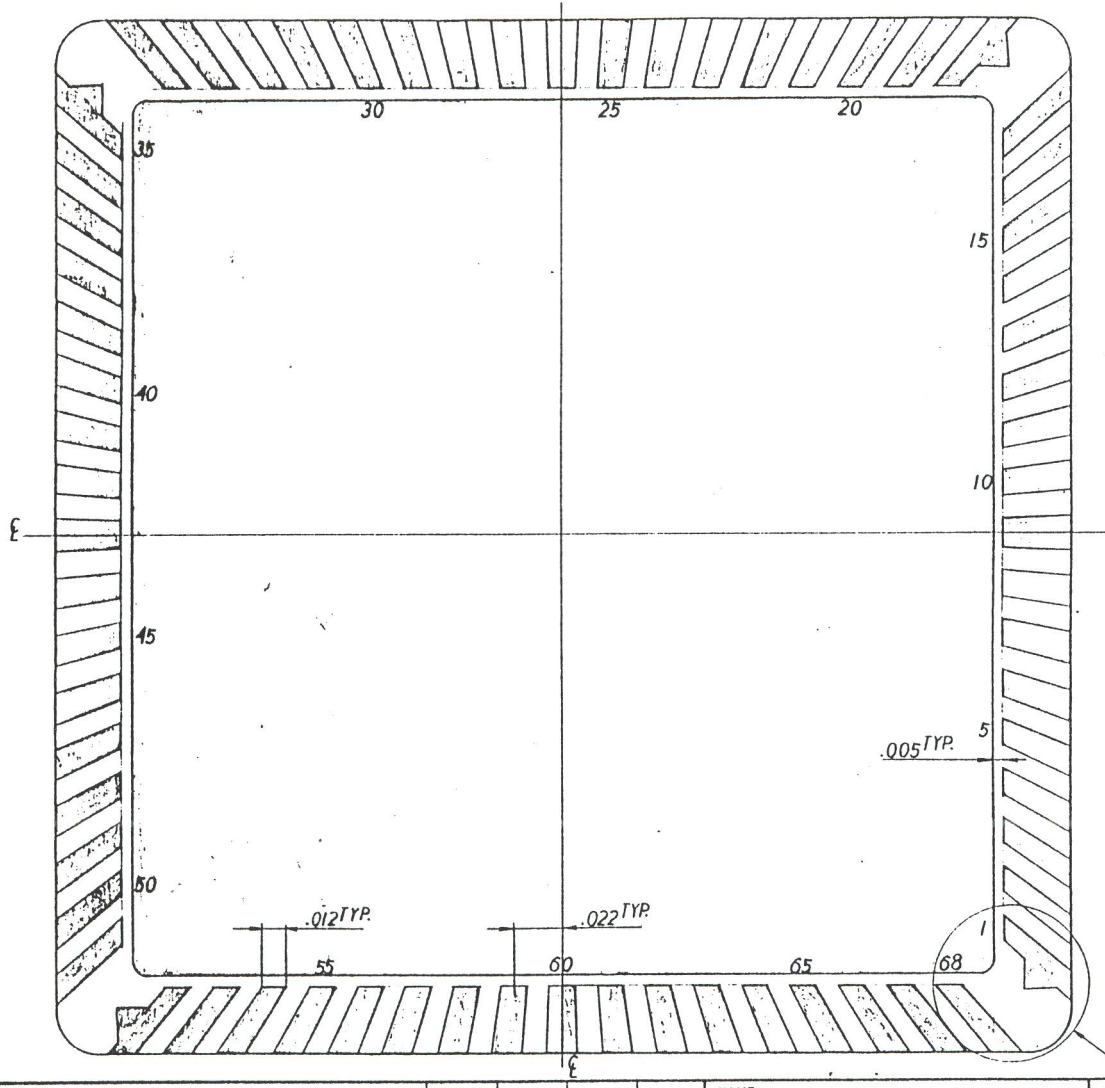


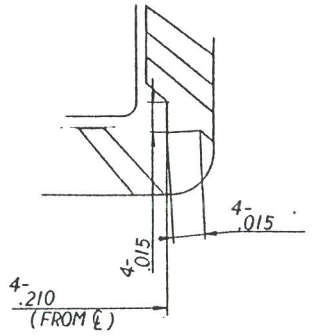
NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
3. SEAL RING TO BE FLOATING FROM ANY PINS.
4. LEAD RESISTANCE: B/F No.1.34.35.68 ····· 200mΩ
   THE OTHERS ····· 500mΩ

MODIFICATIONS	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME: 68 PIN GRID ARRAY PACKAGE	TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1.0% N.L.T. ±.005	DRAWN: S. Minami	CHECKED: S. Abe
SCALE: 5 : 1	MATERIAL: AS INDICATED	APPROVED:	DATE: Jun. 16. '86
KYOCERA CORPORATION KYOTO JAPAN		DWG.NO. KD-P86595	1/3



BONDING PATTERN



DETAIL A

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME: 68 PIN GRID ARRAY PACKAGE
SCALE: 20 : 1
MATERIAL:
TOLERANCES: UNLESS OTHERWISE SPECIFIED

DRAWN	CHECKED
S. Minami	S. Abe
APPROVED	DATE
	Jun.16.'86

KYOCERA CORPORATION KYOTO JAPAN
DWG.NO. KD-P86595
2/3

WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

BONDING PAD	PIN No.
1	B 2
2	B 1
3	C 2
4	C 1
5	D 2
6	D 1
7	E 2
8	E 1
9	F 2
10	F 1
11	G 2
12	G 1
13	H 2
14	H 1
15	J 2
16	J 1
17	K 1
18	K 2
19	L 2
20	K 3
21	L 3
22	K 4
23	L 4

BONDING PAD	PIN No.
24	K 5
25	L 5
26	K 6
27	L 6
28	K 7
29	L 7
30	K 8
31	L 8
32	K 9
33	L 9
34	L 10
35	K 10
36	K 11
37	J 10
38	J 11
39	H 10
40	H 11
41	G 10
42	G 11
43	F 10
44	F 11
45	E 10
46	E 11

BONDING PAD	PIN No.
47	D 10
48	D 11
49	C 10
50	C 11
51	B 11
52	B 10
53	A 10
54	B 9
55	A 9
56	B 8
57	A 8
58	B 7
59	A 7
60	B 6
61	A 6
62	B 5
63	A 5
64	B 4
65	A 4
66	B 3
67	A 3
68	A 2

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME: 68 PIN GRID ARRAY PACKAGE
SCALE: —
MATERIAL: —
TOLERANCES: UNLESS OTHERWISE SPECIFIED —

DRAWN	CHECKED
S. Minami	S. Abe
APPROVED	DATE
	Jun.16.'86

KYOCERA CORPORATION KYOTO JAPAN

DWG.NO. KD-P86595